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**Aehr Test Systems to Participate at the Craig-Hallum Alpha Select Conference
in New York on November 16, 2017**

Fremont, CA (November 9, 2017) - Aehr Test Systems (NASDAQ: AEHR), a worldwide supplier of semiconductor test and burn-in equipment, today announced it has been invited to participate at the eighth annual Craig-Hallum Alpha Select Conference on November 16, 2017 at the Sheraton New York Times Square Hotel in New York City.

Gayn Erickson, President and CEO, and Ken Spink, CFO, will host one-on-one and small group meetings with institutional investors throughout the day. To schedule a meeting, please contact either your Craig-Hallum representative, or the MKR Group, Aehr Test's investor relations firm, at aehr@mkr-group.com.

About Aehr Test Systems

Headquartered in Fremont, California, Aehr Test Systems is a worldwide provider of test systems for burning-in and testing logic, optical and memory integrated circuits and has an installed base of more than 2,500 systems worldwide. Increased quality and reliability needs of the Automotive and Mobility integrated circuit markets are driving additional test requirements, incremental capacity needs, and new opportunities for Aehr Test products in package, wafer level, and singulated die/module level test. Aehr Test has developed and introduced several innovative products, including the ABTS™ and FOX-P™ families of test and burn-in systems and FOX WaferPak Aligner, FOX-XP WaferPak Contactor, and FOX DiePak® Carrier. The ABTS system is used in production and qualification testing of packaged parts for lower power and higher power logic devices as well as all common types of memory devices. The FOX-XP system is a full wafer contact and singulated die/module test and burn-in system used for burn-in and functional test of complex devices, such as leading-edge memories, digital signal processors, microprocessors, microcontrollers, systems-on-a-chip, and integrated optical devices. The WaferPak contactor contains a unique full wafer probe card capable of testing wafers up to 300mm that enables IC manufacturers to perform test and burn-in of full wafers on Aehr Test FOX systems. The DiePak Carrier is a reusable, temporary package that enables IC manufacturers to perform cost-effective final test and burn-in of both bare die and modules. For more information, please visit Aehr Test System's website at www.aehr.com.

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